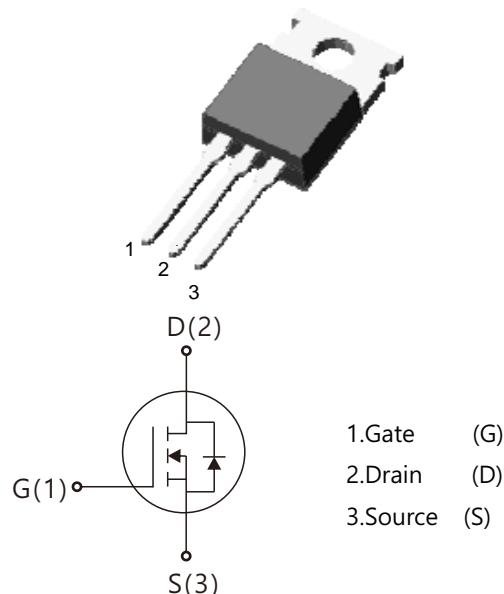




Features:

- High Voltage: $BV_{DSS}=80V$ (Min.)
- Low C_{rss} : $C_{rss}=24.4\text{pF}(\text{Typ.})$
- Low gate charge : $Q_g=55.7\text{nC}(\text{Typ.})$
- Low $R_{DS(on)}$: $R_{DS(on)} =5.2\text{m}\Omega(\text{Typ.})$

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Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Characteristic	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	80	V
Gate-source voltage	V_{GSS}	± 20	V
Drain current (DC) *	I_D	$T_C=25^\circ\text{C}$	A
		$T_C=100^\circ\text{C}$	A
Drain current (Pulsed) *	I_{DM}	480	A
Drain power dissipation	P_D	150	W
Avalanche current (Single) ②	I_A	120	A
Single pulsed avalanche energy ②	E_{AS}	300	mJ
Avalanche current (Repetitive) ①	I_{AR}	120	A
Repetitive avalanche energy ①	E_{AR}	8.6	mJ
Junction temperature	T_J	150	°C
Storage temperature range	T_{stg}	-55~150	°C

* Limited by maximum junction temperature

Characteristic	Symbol	Typ.	Max	Unit
Thermal resistance	Junction-case	$R_{th(J-C)}$	-	5.0
	Junction-ambient	$R_{th(J-A)}$	-	60 °C/W



Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$I_D=250 \mu\text{A}, V_{GS}=0\text{V}$	80	85	-	V
Gate threshold voltage	$V_{GS(\text{th})}$	$I_D=250 \mu\text{A}, V_{GS}=V_{DS}$	2.5	-	3.5	V
Drain-source cut-off current	I_{DSS}	$V_{DS}=80\text{V}, V_{GS}=0\text{V}$	-	-	1	μA
Gate leakage current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
Drain-source on-resistance ⁽⁴⁾	$R_{DS(\text{on})}$	$V_{GS}=10\text{V}, I_D=20\text{A}$	-	5.2	6	$\text{m}\Omega$
Forward transfer conductance ⁽⁴⁾	g_{fs}	$V_{DS}=10\text{V}, I_D=20\text{A}$	-	5	-	S
Input capacitance	C_{iss}	$V_{GS}=0\text{V}, V_{DS}=40\text{V}$ $f=1 \text{ MHz}$	-	3730	-	pF
Output capacitance	C_{oss}		-	670	-	
Reverse transfer capacitance	C_{rss}		-	24.4	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=40\text{V}, I_D=10.0\text{A}$ $R_G=10\Omega$	-	16.5	-	ns
Rise time	t_r		-	13.7	-	
Turn-off delay time	$t_{d(off)}$		-	35.9	-	
Fall time	t_f		-	13.5	-	
Total gate charge	Q_g	$V_{DS}=40\text{V}, V_{GS}=10\text{V}$ $I_D=20.0\text{A}$	-	55.7	-	nC
Gate-source charge	Q_{gs}		-	14.5	-	
Gate-drain charge	Q_{gd}		-	14	-	

Source-Drain Diode Ratings and Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Source current (DC)	I_S	Integral reverse diode in the MOSFET	-	-	120	A
Source current (Pulsed) ⁽¹⁾	I_{SP}		-	-	480	
Forward voltage ⁽⁴⁾	V_{SD}	$V_{GS}=0\text{V}, I_S=18\text{A}$	-	-	1.4	V
Reverse recovery time	t_{rr}	$I_S=20\text{A}, V_{GS}=0\text{V}$ $dI_S/dt=100\text{A}/\mu\text{s}$	-	40	-	ns
Reverse recovery charge	Q_{rr}		-	1.0	-	μC

Note :

- ① Repetitive rating : Pulse width limited by maximum junction temperature
- ② $L=2.0\text{mH}, I_{AS}=10\text{A}, V_{DD}=50\text{V}, R_G=25\Omega$, Starting $T_J = 25^\circ\text{C}$
- ③ Pulse Test : Pulse width $\leq 300 \mu\text{s}$, Duty cycle $\leq 2\%$
- ④ Essentially independent of operating temperature



Electrical Characteristic Curves

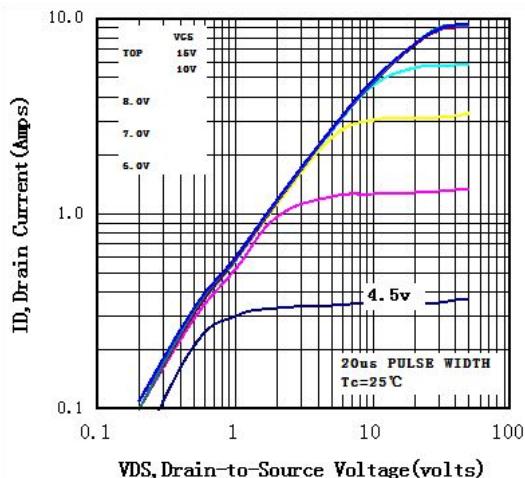


Fig1 Typical Output Characteristics, $T_c=25$

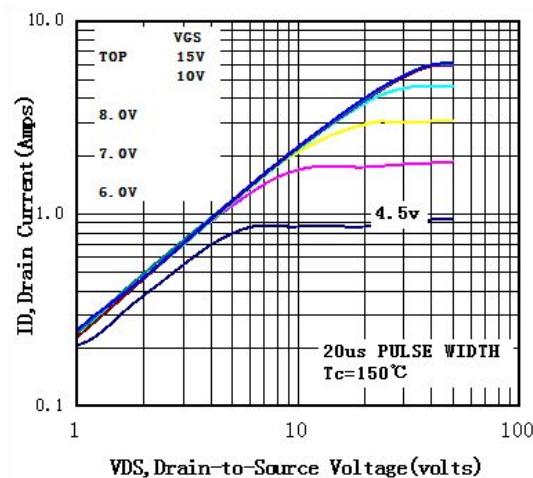


Fig2 Typical Output Characteristics, $T_c=150$

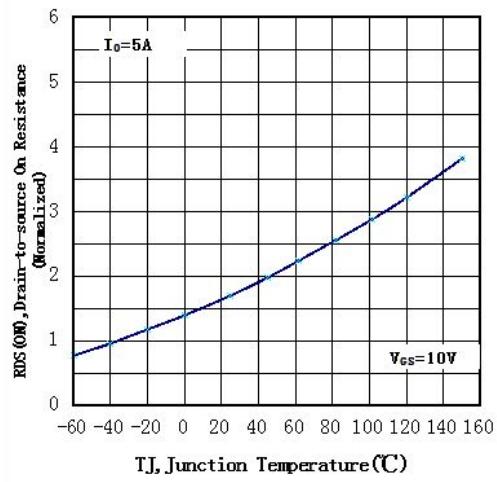


Fig3 Normalized Resistance Vs.Temperature Fig4 Typical Source-Drain Diode Forward Voltage

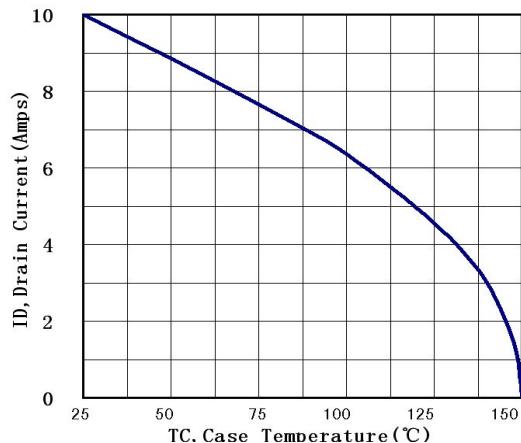
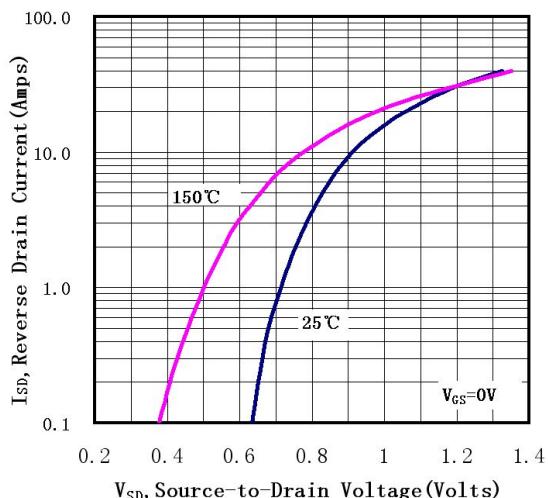


Fig5 Maximum Drain Current Vs.Case Temperature



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Fig. 11 Gate Charge Test Circuit & Waveform

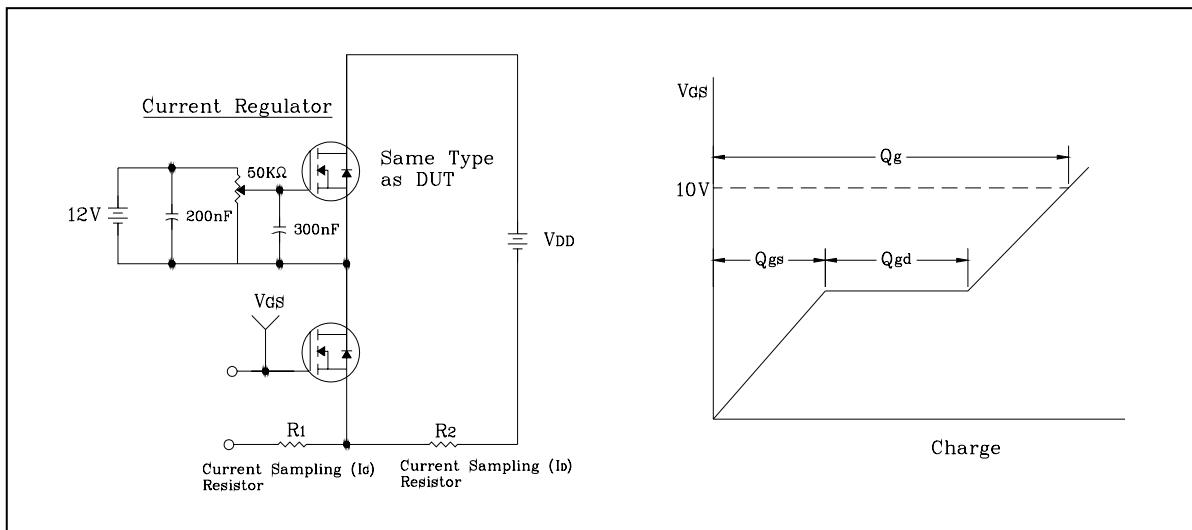


Fig. 12 Resistive Switching Test Circuit & Waveform

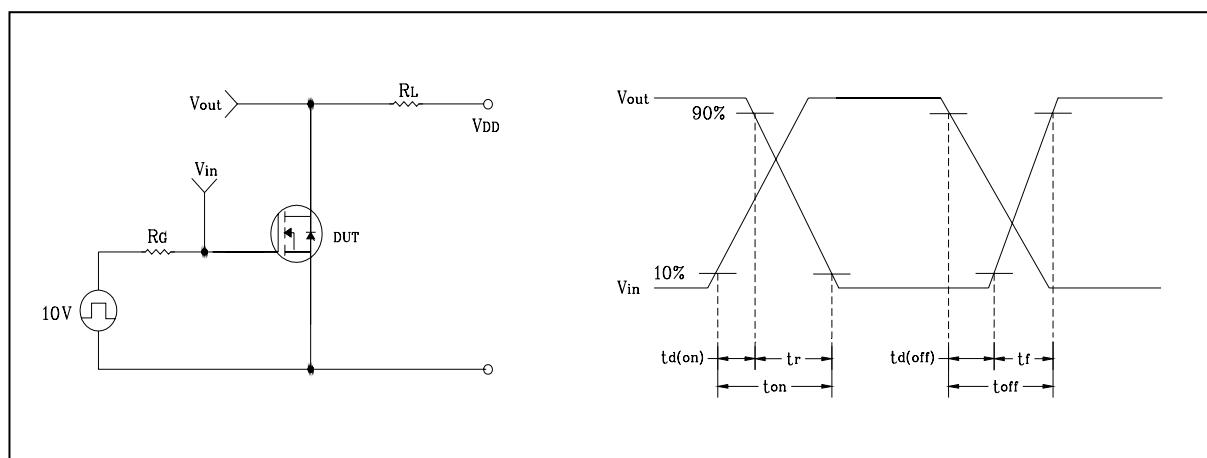
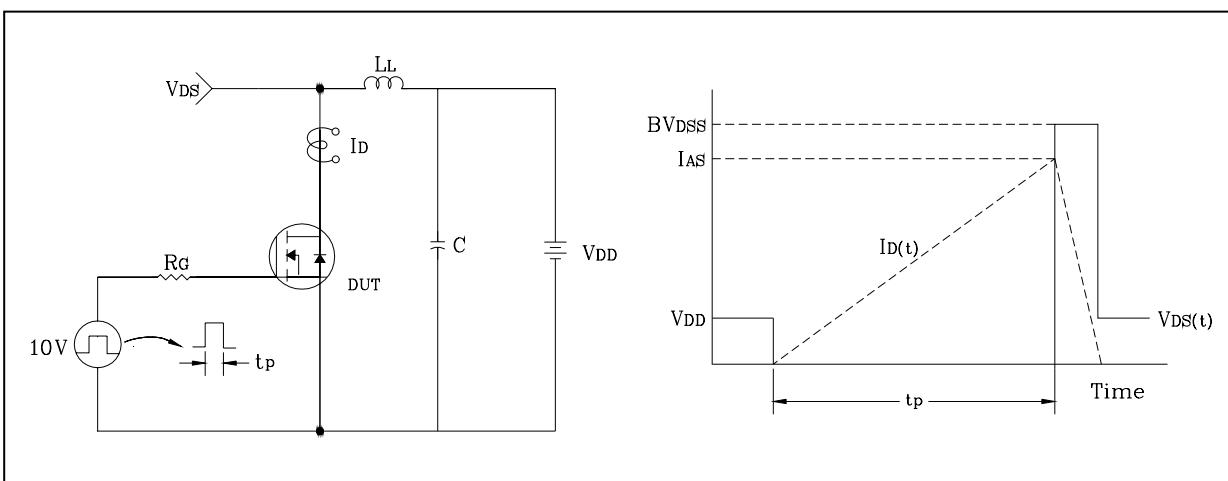


Fig. 13 E_{AS} Test Circuit & Waveform

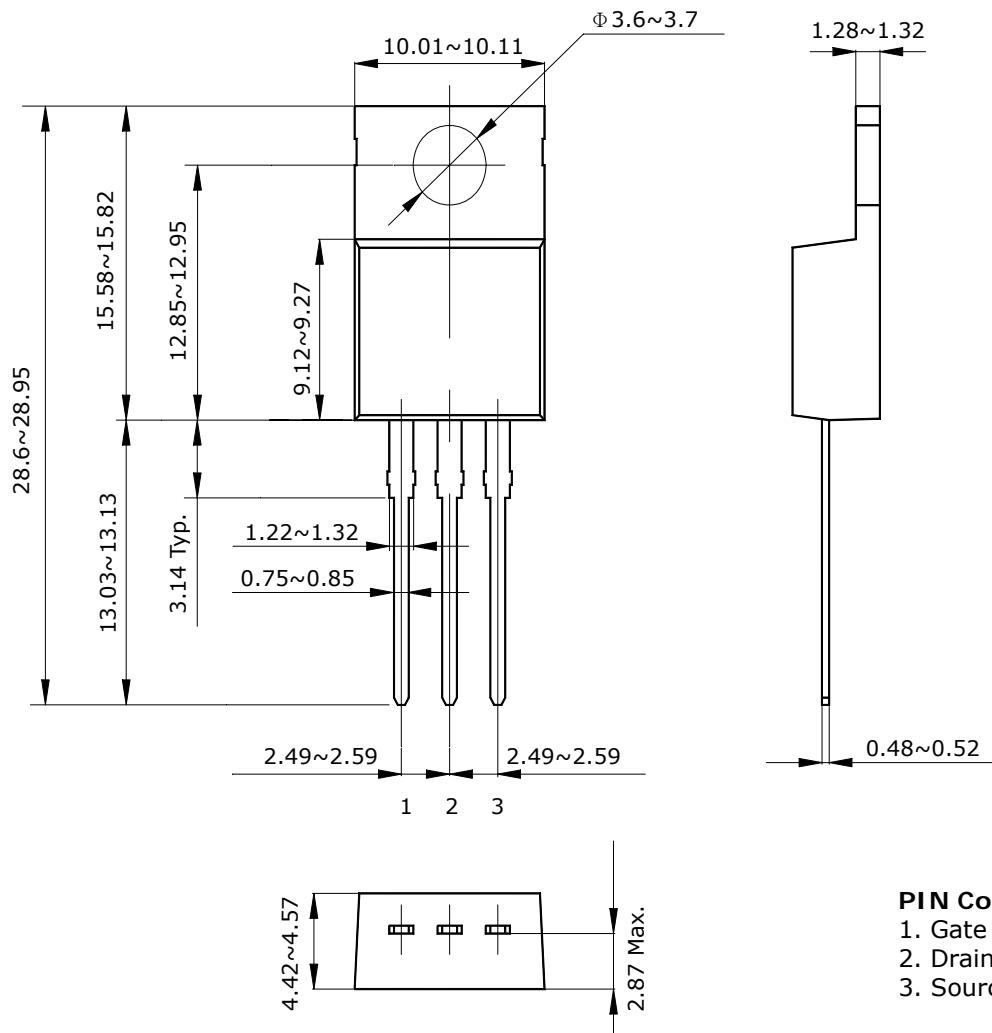




HGS120N80C 80V N-Channel MOSFET

TO-220-3L Package Information

unit : mm



PIN Connections

1. Gate
2. Drain
3. Source